





Surface mount package with heat transfer feature

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Abstract of corresponding document: **US5679979**

A package (1) for diodes (6) is constructed with a substrate (2) of alumina, a common area (5) on which diodes (6) are mounted, bond wires (8) extending from respective diodes to connect with respective conducting output areas (9) respective vias (13) connecting the common area (5) and the output areas (9) to respective surface mount pads (14, 18) on a bottom surface of the substrate (2), heat spreading areas (19) on the top surface of the substrate (2), and multiple conducting vias (13) connecting each of the heat spreading areas (19) to a heat conducting, surface mount, ground pad (20) on the bottom surface of the substrate (2).

